

SOD80C

hermetically sealed glass surface-mounted package; 2 connectors

8 February 2016

Package information

1. Package summary

Terminal position code	E (end)
Package type descriptive code	LLDS; MiniMelf
Package type industry code	LLDS; MiniMelf
Package style descriptive code	MELF (metal electrode leadless face)
Package style suffix code	NA (not applicable)
Package body material type	L (glass)
IEC package outline code	100H01
Mounting method type	S (surface mount)
Issue date	16-3-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.3	-	3.5	3.7	mm
Φ D	package diameter	1.45	-	1.5	1.6	mm
n ₂	actual quantity of termination	-	-	2	-	



2. Package outline

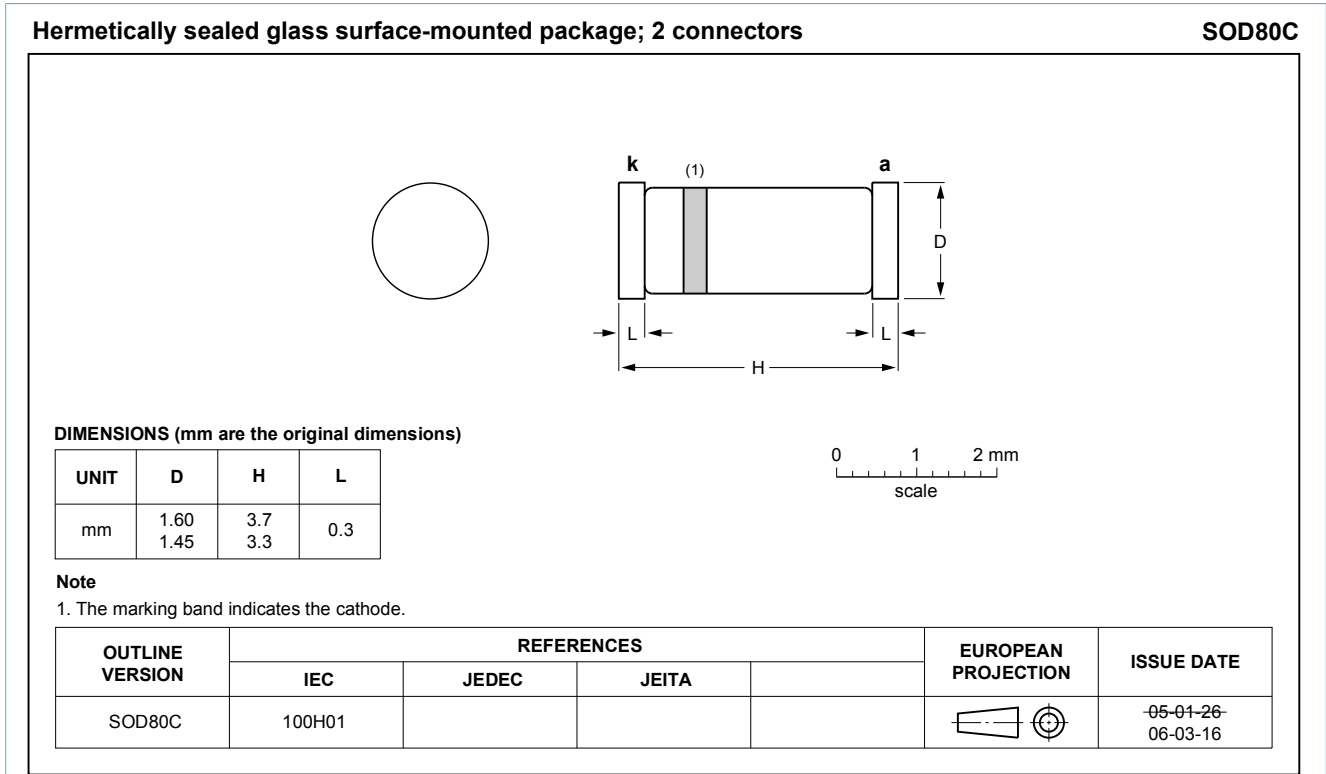


Fig. 1. Package outline LLDS; MiniMelf (SOD80C)

3. Soldering

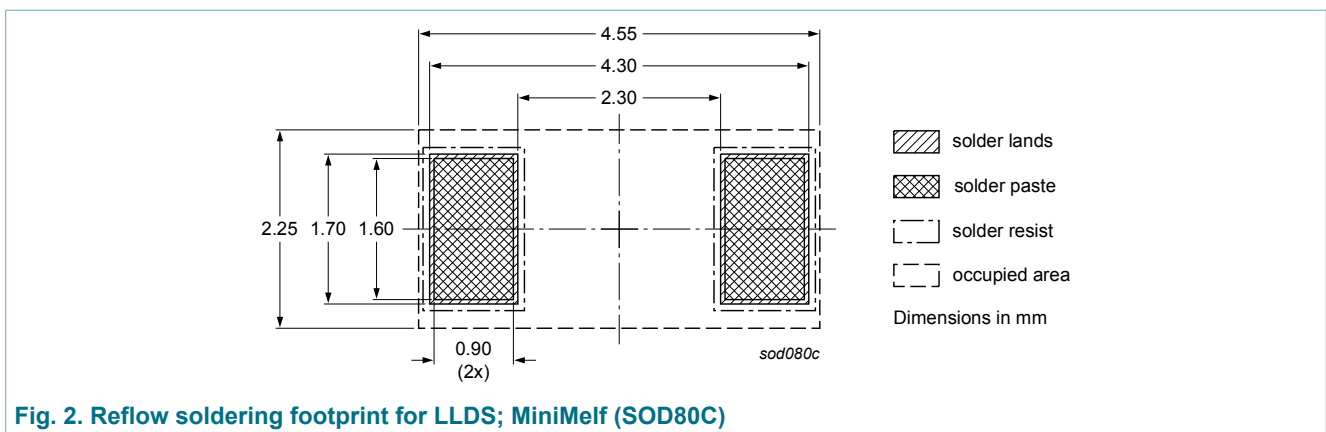


Fig. 2. Reflow soldering footprint for LLDS; MiniMelf (SOD80C)

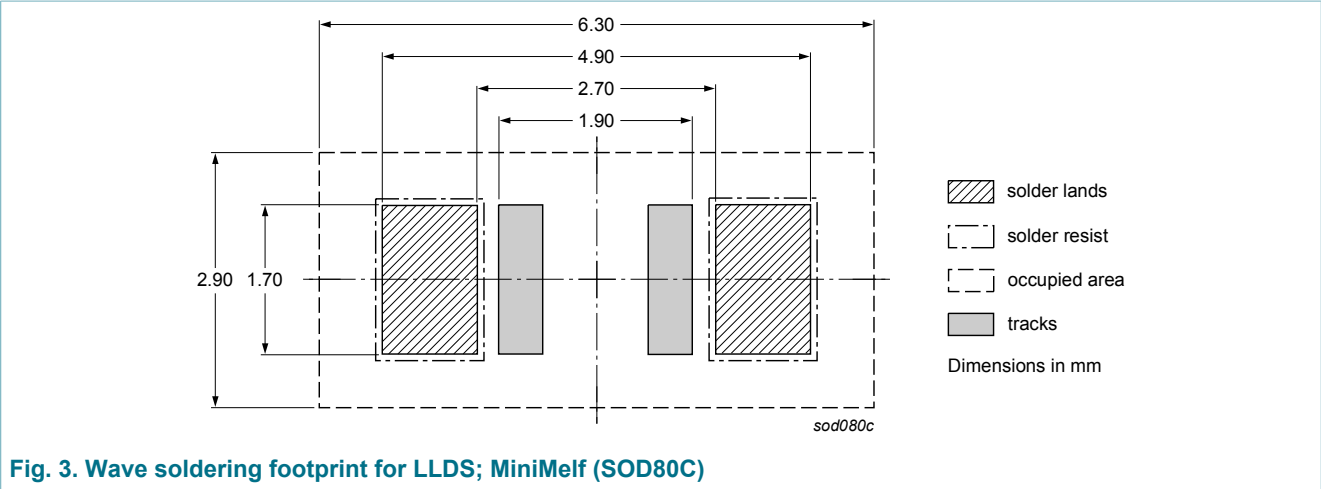


Fig. 3. Wave soldering footprint for LLDS; MiniMelf (SOD80C)

4. Legal information

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